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Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		$V_{RM}$	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	75	٧
RMS Reverse Voltage		V <sub>R(RMS)</sub>	53	V
Forward Continuous Current		I <sub>FM</sub>	500	mA
Average Rectified Output Current		lo	250	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0s	I <sub>FSM</sub>	4 0.5	А

### **Thermal Characteristics**

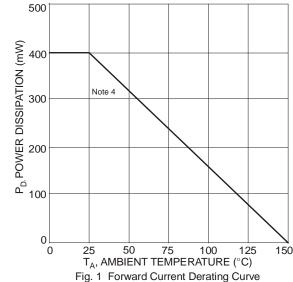
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P <sub>D</sub>	400	mW
Thermal Resistance Junction to Ambient Air (Note 4)	$R_{ heta JA}$	313	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

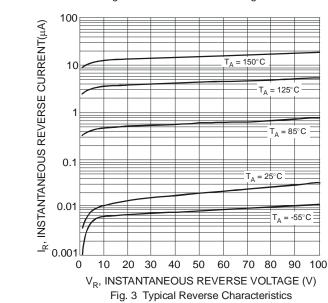
# **Electrical Characteristics** @TA = 25°C unless otherwise specified

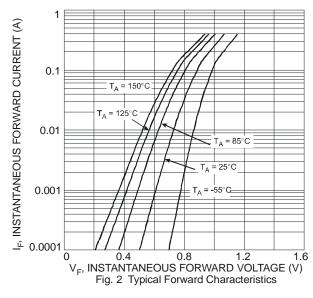
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	75	_	V	$I_R = 100 \mu A$
		0.62	0.72	V	$I_F = 5.0 \text{mA}$
Forward Voltage	V <sub>F</sub>	_	0.855		$I_F = 10mA$
Tolward Voltage	VF	_	1.0		$I_F = 100 \text{mA}$
		_	1.25		I <sub>F</sub> = 150mA
		_	2.5	μΑ	$V_R = 75V$
Leakage Current (Note 5)	1 -	_	50	μΑ	$V_R = 75V, T_J = 150^{\circ}C$
Leakage Current (Note 5)	I <sub>R</sub>	_	30	μΑ	V <sub>R</sub> = 25V, T <sub>J</sub> = 150°C
		_	25	nA	$V_R = 20V$
Total Capacitance	CT	_	4.0	pF	$V_R = 0$ , $f = 1.0MHz$
Reverse Recovery Time	t <sub>rr</sub>	_	4.0		$I_F = I_R = 10 \text{mA},$
Treverse recovery fillic	чr				$I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$

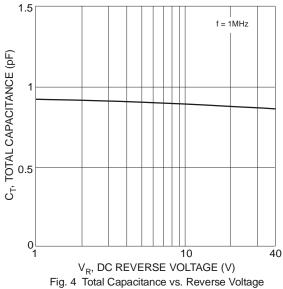
4. Part mounted on FR-4 PC board with minimum recommended pad layouts, which can be found on our website at http://www/diodes.com. 5. Short duration pulse test used to minimize self-heating. Notes:



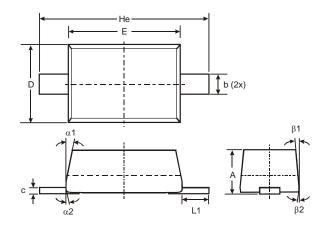








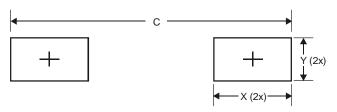
## **Package Outline Dimensions**



SOD323F				
Dim	Min	Max	Тур	
Α	0.60	0.75	-	
b	0.25	0.35	-	
С	0.05	0.26	-	
D	1.15	1.35	1.25	
Е	1.60	1.80	1.70	
He	2.30	2.70	2.50	
L1	0.30	0.50	0.40	
α1	-	-	7°	
α2	-	-	3°	
β1	-	-	7°	
β2	-	-	3°	
All Dimensions in mm				



### **Suggested Pad Layout**



Dimensions	Value (in mm)
Х	0.710
Y	0.403
С	2.700

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